

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	92648	inspect\$3 and(wafer\$I or semicondutor\$I or chip\$I or subtrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:49
L3	57	inspect\$3 and formation adj state and (wafer\$I or semicondutor\$I or chip\$I or subtrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:50
L4	45	L3 and(@ad<"20031222" or @rlad<"20031222" or @prad<"20031222" or @ptad<"20031222")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:54
L5	39	L3 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:54
L6	0	L5 and generat\$3 and inspect\$3 adj data same pattern adj area same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:56
L7	2	inspect\$3 adj data same pattern adj area same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:57
L8	39	L5 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:57
L9	0	L8 and inspect\$3 adj data same pattern adj area same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:58
L10	0	L8 and inspect\$3 adj data and pattern adj area and inside and outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:58

L11	4	L8 and inspect\$3 and pattern adj area and inside and outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:59
L12	4	L11 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:59
L13	4	L12 and inside and outside	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:03
L14	4	L12 and inside and outside and pattern adj(area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:04
L15	4	L12 and inside and outside and pattern adj(area or regions)and (comapar\$5 or match\$ or combining)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:05
L16	4	L12 and inside and outside and pattern adj(area or regions)and (comapar\$5 or match\$ or combining) and(difference or differ or sum)and (luminance or shapes)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:07
L17	109	("5723236" "4783826" "5608816" "5892224" "5917590" "6166808" "4319270" "4760265" "4897795" "4943186" "5324568" "5331432" "5362591" "5404410" "5621825" "5656397" "5659172" "5665645" "5691543" "5838433" "5885735" "6038015" "6043870" "6052170" "6219807" "6219807" "3806015" "4056716" "4156231" "4244650" "4247748" "4255055" "4270863" "4286266" "4286146" "4295200" "4296474" "4297818" "4311267" "4318590" "4319269" "4320567" "4321534" "4330775" "4339952" "4344146" "4357540" "4365163" "4366564" "4396509" ).pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:20
L18	0	L17 and inspect\$3 and formation adj state and(wafer\$I or semicondudor\$I or chip\$I or subtrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:23

L19	0	L17 and inspect\$3 adj data same pattern adj area same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:24
L20	22	L17 and inspect\$3 and(wafer\$I or semicondutor\$I or chip\$I or subtrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:25
L21	22	L20 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:25
L22	92648	inspect\$3 and(wafer\$I or semicondutor\$I or chip\$I or subtrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:50
L23	2	L22 and(generat\$3 or obtaining)and inspect\$3 adj data same pattern adj area same inside adj pattern same outside adj pattern and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:52
L24	2	L22 and(generat\$3 or obtaining)and inspect\$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:53
L25	2	(generat\$3 or obtaining)and inspect \$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:53
L26	20	(generat\$3 or obtaining)and inspect \$3 and(region or area)adj pattern and inside adj pattern and outside adj pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:55
L27	14	L26 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:55
L28	0	L8 and inspect\$3 adj data same pattern adj area same object same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:19

L29	0	L26 and inspect\$3 adj data same pattern adj area same object same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:19
L30	1	L26 and inspect\$3 adj data and pattern adj area and(object or patterns)same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:20
L31	0	L30 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:20
L32	5	L2 and inspect\$3 adj data and pattern adj area and(object or patterns)same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:21
L33	3	L32 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:21
L34	12243	430/5,322.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:43
L35	5206	430/5,322.CCLS.	USPAT	OR	ON	2009/04/20 13:44
L36	505	L35 and inspect\$3 and(wafer\$I or semiconductor\$I or chip\$I or subtrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	USPAT	OR	ON	2009/04/20 13:44
L37	0	L36 and(generat\$3 or obtaining)and inspect\$3 and(region or area)adj pattern and inside adj pattern and outside adj pattern	USPAT	OR	ON	2009/04/20 13:45
L38	29	L36 and inspect\$3 and pattern adj area and inside and outside and inspect\$3	USPAT	OR	ON	2009/04/20 13:47
L39	5	L38 and inside and outside and pattern adj(area or regions)and (comapar\$5 or match\$ or combining)	USPAT	OR	ON	2009/04/20 13:48
L40	5	L39 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:48
L41	2132	382/149,209,141,147,149..CCLS.	USPAT	OR	ON	2009/04/20 13:50

L42	2132	382/149,209,141,147,149.CCLS.	USPAT	OR	ON	2009/04/20 13:50
L43	508	L42 and inspect\$3 and(wafer\$I or semiconductor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	USPAT	OR	ON	2009/04/20 13:51
L44	0	L43 and(generat\$3 or obtaining)and inspect\$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:51
L45	49494	inspect\$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:53
L46	17	L45 and inspect\$3 adj data and pattern adj area and(object or patterns or pads or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:54
L47	11	L46 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:55
L48	24563	inspect\$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	USPAT	OR	ON	2009/04/20 13:57
L49	2	"chawan_sheela." "XA."	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:58
L50	1651	chawan sheela.xa.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:03
L51	1859	chawan sheela.xp.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:03
L52	53	L50 and inspect\$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	USPAT	OR	ON	2009/04/20 14:06
L53	54	L50 and inspect\$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:06

L54	49	L51 and inspect\$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:06
L55	0	L53 and(generat\$3 or obtaining)and inspect\$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:07
L56	0	L54 and(generat\$3 or obtaining)and inspect\$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:07
L57	47	L53 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:08
L58	44	L54 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:08
L59	1	L24 and inspect\$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:53
L60	55	inspect\$3 and formation adj state and (wafer\$I or semicondutor\$I or chip\$I or subtrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:55
L61	1	L60 and inspect\$3 adj data same (inside or interior)same luminance same (exterior or outside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:58
L62	38	L60 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:58
L63	0	L62 and inspect\$3 adj data same (inside or interior)same luminance same (exterior or outside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:58
L64	0	L62 and inspect\$3 adj data and measuring and(inside or interior)and luminance and shape and(exterior or outside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:00

L65	2	pattern adj inspect\$3 same(inside or exterior)adj(area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:17
L66	2	L65 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:18
L67	0	L66 and pattern adj inspect\$3 same (outside or exterior)adj(area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:19
L68	2	pattern adj inspect\$3 same(inside or interior)adj(area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:19
L69	0	L68 and pattern adj inspect\$3 same (outside or exterior)adj(area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:20
L70	3	L3 and(generat\$3 or obtaining)and inspect\$3 adj data and pattern adj (area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:30
L71	0	L70 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:31
L72	0	L3 and(generat\$3 or obtaining)and inspect\$3 adj data and pattern adj (area or region)and difference adj image\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:33
L73	37	(generat\$3 or obtaining)and inspect \$3 adj data and pattern adj(area or region)and difference adj image\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:33
L74	25	L73 and pattern adj inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:33
L75	21	L74 and (outline or edge or contour)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:34

L76	0	L75 and inspect\$3 adj data same luminance same shape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:48
L77	2	L75 and inspect\$3 adj data and luminance and shape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:49
L78	2	L77 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:49
L79	2	"6327379".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 16:51
L80	2	L79 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 16:51
L81	0	L80 and difference	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 16:53

**4/ 20/ 09 4:54:21 PM**

**C:\ Documents and Settings\ Schawan\ My Documents\ EAST\ Workspaces\ 3660.wsp**